

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A prepreg for a printed wiring board material comprising a thermosetting resin (D) composition containing, as an essential component, an aluminum hydroxide-boehmite composite (A) obtained by hydrothermal treatment of aluminum hydroxide, boehmite (B), and a substrate (I), wherein the weight ratio of the aluminum hydroxide-boehmite composite (A) to boehmite (B) is in the range of from 45:55 to 95:5, and the weight ratio of aluminum hydroxide to boehmite in the aluminum hydroxide-boehmite composite (A) is in the range of from 45:55 to 95:5.

2. (Canceled)

3. (Currently Amended) A The prepreg according to claim 1, wherein the amount of the aluminum hydroxide-boehmite composite (A) per 100 parts by weight of the thermosetting resin (D) is 1 to 200 parts by weight.

4. (Currently Amended) A The prepreg according to claim 1, wherein the thermosetting resin (D) composition further contains a silane coupling agent (E) ~~or a wetting dispersing agent (F).~~

5. (Canceled)

6. (Canceled)

7. (Canceled)

8. (Currently Amended) A The prepreg according to claim 1, wherein the thermosetting resin (D) contains a cyanate ester resin (G) or a nonhalogenated epoxy resin (H).

9. (Currently Amended) A The prepreg according to claim 8,

wherein the cyanate ester resin (G) is 2,2-bis(4-cyanatophenyl)propane, cyanates obtained by a reaction between novolak and cyan halide, or a mixture of these.

10. (Currently Amended) A The prepreg according to claim 8,

wherein the nonhalogenated epoxy resin (H) is one member or at least two members selected from the group consisting of a bisphenol F type epoxy resin, a phenol novolak type epoxy resin, a cresol novolak type epoxy resin, a polyfunctional phenol type epoxy resin, a naphthalene type epoxy resin, a biphenyl novolak type epoxy resin and a phosphorus-containing epoxy resin.

11. (Original) A laminate obtained by stacking the prepreg as recited in claim 1.

12. (Original) A metal-foil-clad laminate obtained by bonding metal foil(s) to one surface or both surfaces of the laminate as recited in claim 11.

13. (New) The prepreg according to claim 1,

wherein the thermosetting resin (D) composition further contains a wetting dispersing agent (F).